Guest Editorial

Advances in Wafer Level Packaging (WLP)

Wafer level packages (WLPs) with various design configurations are rapidly gaining tremendous applications throughout semiconductor industry due to small-form factor, low-cost, and high

actual reliability of WLP under uniaxial loading, which is commonly observed in drop simulations and tests of mobile devices.

We are grateful to the participating authors and reviewers, who have devoted to the subject and altogether contributed to this special issue in many ways. We hope the readers will enjoy this special issue, and look forward to your feedback and future contributions in this field.

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